SOP-8 物 料 成 分 表

Material Composition Data

构成部件 Sub-part(if yes)		构成成分 Composition	CAS编号 CAS No.	化学成分%
英文名称 English	重量(mg) Weight	英文名称 English		
Die	3	Si	7440-21-3	100.00%
Lead Frame	32.9	Cu	7440-50-8	balance
		Fe	7439-89-6	2.1-2.6
		P	7723-14-0	0.015-0.15
		Zn	7440-66-6	0.05-0.20
		Pb	7439-92-1	≤0.005
Epoxy	0.343	Silver	7440-22-4	60-100%
		Epoxy Resin.	-	10-30%
		1,4-bis(2,3 epoxypropoxy)butane	2425-79-8	5-10%
		Aromatic polyamine Proprietary	-	1-5%
Wire	0.686	Copper	231-159-6	≥99.99
		Silver	231-131-3	<20ppm
		other	-	-
Mold Compound	40.2	Epoxy Resin A	Trade Secret	1-5%
		Epoxy Resin B	29690-82-2	1-5%
		Phenol Resin	Trade Secret	1-5%
		Silica(Amorphous)A	60676-86-0	70-90%
		Silica(Amorphous)B	7631-86-9	1-5%
		Carbon Black	1333-86-4	0.1-1%
Plating	0.89	Sn	7440-31-5	99.99%
Total	78			

Notes: Lead in internal soft solder, ROHS exemption clause Annex 7a"lead in high melting temperature type solders" applied.Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the information, it is for guidance only and we cannot guarantee to its accuracy or completeness.